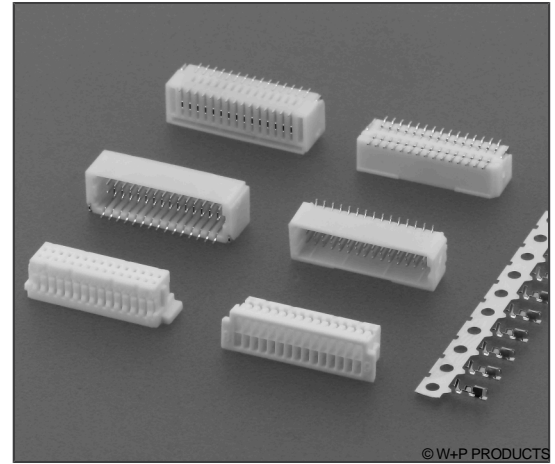


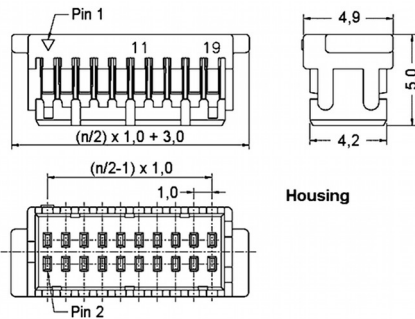
## SMT-Crimp-Rast-Stift-/Buchsenleisten RM 1,00mm, stehend/liegend SMT Friction Lock Headers / Crimp Housings, 1.00mm Pitch, Vertical/Horizontal

### Technische Daten / Technical Data

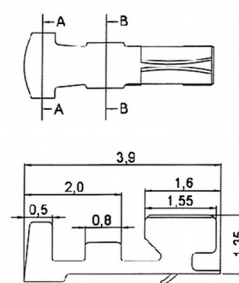
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Aderquerschnitt	AWG 32 ~ 28
Applicable wire Gauge	AWG 32 ~ 28
Durchgangswiderstand	< 20 mΩ at initial state
Contact Resistance	< 20 mΩ at initial state
Isolationswiderstand	> 100 MΩ
Insulation Resistance	> 100 MΩ
Spannungsfestigkeit	500 V AC
Test Voltage	500 V AC
Nennspannung	50 V AC
Voltage Rating	50 V AC
Nennstrom	1 A mit AWG 28
Current Rating	1 A with AWG 28
Temperaturbereich	-25 °C ... +85 °C
Temperature Range	-25 °C ... +85 °C
Verarbeitung	Reflow-Lötverfahren
Processing	Reflow soldering



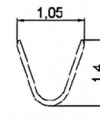
© W+P PRODUCTS



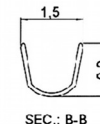
Housing



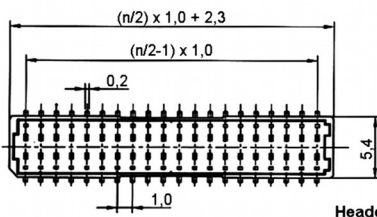
Contact



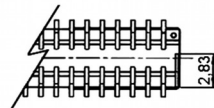
SEC.: A-A



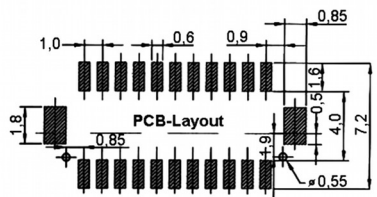
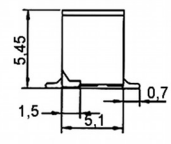
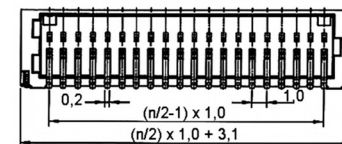
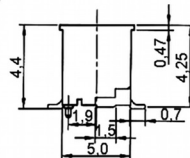
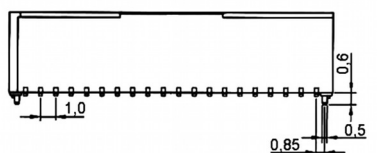
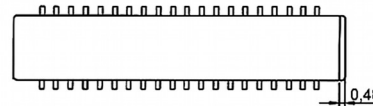
SEC.: B-B



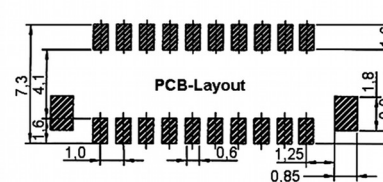
Header - Straight



Header - Right Angled



PCB-Layout



PCB-Layout

### Series

**5111**

### Contacts\*

**20**

20/30/40/50  
01 (für Buchsenkontakte)  
(for crimp contacts)

### Type\*

**3**

1 Buchsengehäuse  
Housing  
2 Buchsenkontakte  
Crimp contacts  
3 Stiftleiste gerade  
Straight pin header  
4 Stiftleiste gewinkelt  
Right-angled pin header

### Plating

**50**

50 Verzinkt (Standard)  
für Gehäuse nicht erforderlich  
Tin plated (Standard)  
(not necessary for housings)

\* Dies ist ein **Bestellbeispiel** -  
bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** -  
please replace by your specifications.

## Informationen zum Reflow-Lötverfahren Reflow Soldering Information

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

